What is claimed is:

1. A manufacturing method for a device in which some or all of plural elements formed on an original substrate are transferred to a final substrate, and some or all of the transferred elements are used to manufacture the device, comprising:

a first process for providing the plural elements on said original substrate via a separation layer in a condition where terminal sections are exposed to a surface on an opposite side to the separation layer;

a second process for adhering the surface where the terminal sections of said elements to be transferred on the original substrate are exposed, via conductive adhesive, to a surface of the final substrate on a side where conductive sections for conducting with the terminal sections of said elements are provided;

a third process for producing exfoliation in said separation layer between said original substrate and said final substrate; and

a fourth process for separating said original substrate from which the transfer of elements has been completed, from said final substrate.

2. A manufacturing method for a device according to claim 1, wherein said original substrate is a substrate for forming elements.

3. A manufacturing method for a device according to one of claim 1 and claim 2, wherein said conductive adhesive is an anisotropic conductive adhesive.

4. A manufacturing method for a device according to claim 3, wherein in said second process, a film-like anisotropic conductive adhesive is used as said conductive

adhesive, and said film-like adhesive is adhered to the surface on the side where the terminal sections of said element are exposed, or to the position to be connected to said terminal sections on the surface of said final substrate on the side where the conductive sections are provided.

5. A manufacturing method for a device according to claim 1, wherein in said second process, said conductive adhesive is provided between the elements and the final substrate in liquid form, and then cured.

6. A manufacturing method for a device according to claim 5, wherein in said second process, said conductive adhesive is selectively arranged by a liquid droplet discharge method.

7. A manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, the position where the conductive adhesive for the elements or for the final substrate is arranged is subjected to a lyophilic treatment, and/or the surroundings of the position where the conductive adhesive is arranged is subjected to a liquid repellent treatment.

8. A manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, a partition is formed to enclose the position where the conductive adhesive for the elements or for the final substrate is arranged, and then, the conductive adhesive is selectively arranged within said partition.

9. A manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, a concavity is formed at a junction position of the elements with the final substrate, and then the conductive adhesive is selectively arranged in said concavity.

10. A manufacturing method for a device according to claim 9, wherein conductive sections for conducting with the terminal sections of said elements are provided beforehand in said concavity.

11. A manufacturing method for a device according to claim 1, wherein in a case where there are plural terminal sections of said elements, the conductive adhesive to be formed on the terminal sections is formed in a condition of independence for each of the respective terminal sections, and between the independent conductive adhesives is insulated.

12. A device comprising elements provided on a substrate, wherein terminal sections are provided in an exposed condition on a surface of said elements on the substrate side, and conductive sections for conducting with the terminal sections of said elements are provided on the surface of said substrate on the side where the elements are provided; and said elements are adhered to said substrate by a conductive adhesive which conducts between said terminal sections and said conductive sections.

13. A device according to claim 12, wherein said conductive adhesive is an anisotropic conductive adhesive.

14. A device according to one of claim 12 and claim 13, wherein there are plural terminal sections of said elements, and the conductive adhesives to be adhered to these terminal sections are formed in a condition of independence for each of the respective terminal sections, and between the independent conductive adhesives is insulated.

15. A device according to claim 14, wherein said conductive adhesives are in the independent condition by arranging the conductive adhesives separated for each of the respective terminal sections, and between the conductive adhesives is insulated.

16. A device according to claim 14, wherein said conductive adhesives are in the independent condition for each of the respective terminal sections by separating by an insulative partition, and between the conductive adhesives is insulated.

17. A device according to claim 14, wherein said conductive adhesives are in the independent condition for each of the respective terminal sections by arranging into respectively independent concavities, and between the conductive adhesives is insulated.

18. A device obtained by a manufacturing method according to claim 1.

19. An electro-optic device equipped with a device according to one of claim 12 and claim 18.

20. An electronic equipment equipped with a device according to one of claim 12 and claim 18.